

Title (en)

COOLING DEVICE FOR PRINTED CIRCUIT BOARDS AND METHOD FOR THE PRODUCTION THEREOF

Title (de)

KÜHLVORRICHTUNG FÜR LEITERPLATTEN UND VERFAHREN ZUR HERSTELLUNG DERSELBEN

Title (fr)

DISPOSITIF DE REFROIDISSEMENT POUR CARTES DE CIRCUITS ET PROCEDE DE PRODUCTION DE CE DISPOSITIF

Publication

**EP 1867224 A2 20071219 (DE)**

Application

**EP 06705989 A 20060218**

Priority

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Abstract (en)

[origin: WO2006105746A2] The invention relates to a cooling device (1) for a printed circuit board (2) which is disposed in a housing (3) and can be connected in a locking manner to a metal cooling element (4) that is embodied as a cover of said housing (3).

IPC 8 full level

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CPC (source: EP US)

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Citation (search report)

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